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(54) Title of the Invention: **Electrical fuse and method of making the same**
Abstract Title: **Electrical fuse and method of making the same**

(57) An improved electrical-fuse (e-fuse) device (200) including a dielectric layer (102) having a first top surface (108), two conductive features (104, 106) embedded in the dielectric layer (102) and a fuse element (122). Each conductive feature (104, 106) has a second top surface (110, 112) and a metal cap (114, 116) directly on the second top surface (110, 112). Each metal cap (114, 116) has a third top surface (118, 120) that is above the first top surface (108) of the dielectric layer (102). The fuse element (122) is on the third top surface (118, 120) of each metal cap (114, 116) and on the first top surface (108) of the dielectric layer (102). A method of forming the e-fuse device (200) is also provided.

